

ESD desoldering braid Soder-Wick®, rosin flux



Soder-Wick Rosin Flux desoldering braid

Soder-Wick® brand desoldering braid offers state-of-the-art desoldering technology. Designed for today's heat-sensitive electronic components, Soder-Wick® is made of a lighter, all-copper braid construction that provides better thermal conductivity even at low temperatures. Soder-Wick® reacts faster than conventional desoldering braids, minimizing overheating and preventing damage to the circuit board.

All desoldering wires are sealed in nitrogen-purged packaging to prevent corrosion and loss of performance due to moisture and oxygen.

Features and benefits

- Soder-Wick® Rosin 5' and 10' coils packaged in ESD-safe, static dissipative coils
- Minimizes the risk of damage from static electricity
- Non-corrosive, ultra-high purity R-type Rosin flux













- Minimizes the risk of heat damage to the circuit board
- Leaves no ionic contamination on the circuit boards Applications
- \bullet Soder-Wick® Rosin safely removes solder in all applications requiring ROL0 type Rosin flux
- BGA braid specifically designed for rework/repair of BGA pads and chips, allowing all BGA pads to be cleaned in three to four passes Specifications:
- MIL-F-14256 F-Typ-R-Flussmittel
- NASA-STD-8739.3 Soldered Electrical Connections
- DOD-STD-883E, Method 2022
- ANSI/IPC J STD-004, Type ROL0

item number	WL86030
manufacturer	CHEMTRONICS
manufacturer item number	SW80-6-5
length	1500 mm
width	5.3 mm
order unit	1 rolls
content unit	1 rolls
colour	red
ESD safe	yes







